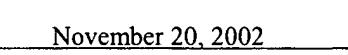




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1/16/03  
PATENT Mullish

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Trivedi et al. ) Group Art Unit 2813  
Appl. No. : 10/038,305 )  
Filed : January 2, 2002 )  
For : METHOD OF FORMING A )  
DUAL DAMASCENE )  
INTERCONNECT (As )  
Amended Herewith) )  
Examiner : T. Nguyen )  
I hereby certify that this correspondence and all  
marked attachments are being deposited with the  
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and Trademark Office, P.O. Box 2327,  
Arlington, VA 22202, on  
November 20, 2002  
(Date)  
  
Adeel S. Akhtar, Reg. No. 41,394  
TECHNOL...

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## **AMENDMENT AND RESPONSE TO OFFICE ACTION**

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed on August 28, 2002, please amend the above-captioned application as follows:

## **IN THE SPECIFICATION:**

Please amend the title paragraph beginning on page 1, line 2 as follows:

## METHOD OF FORMING A DUAL DAMASCENE INTERCONNECT

**IN THE CLAIMS:**

Please amend the following claim:

*SUBC17* 11. (Amended) A method for fabricating an integrated circuit interconnect structure, comprising:

etching a pattern of dual damascene trenches and contact vias in insulating material;

preferentially depositing a first metal into the contact vias to partially fill the contact vias; and